

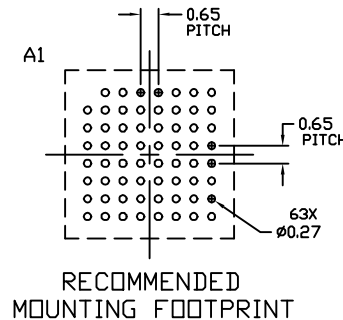
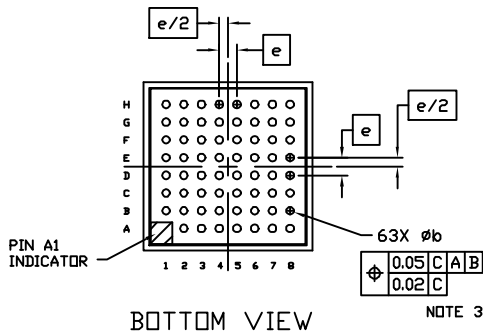
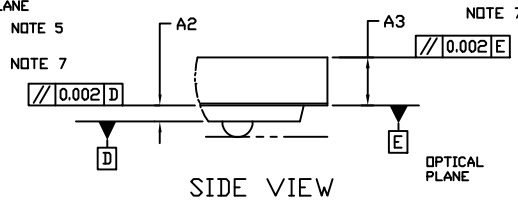
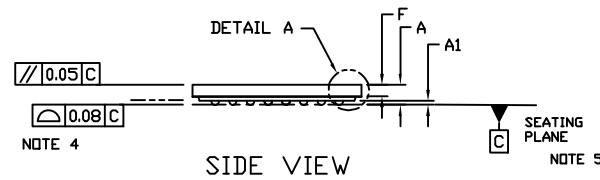
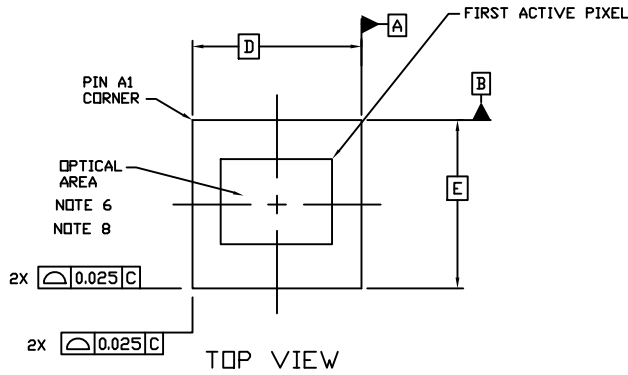
# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



ODCSP63, 6.198x6.178  
CASE 570BY  
ISSUE B

DATE 05 JAN 2018



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. MAXIMUM ROTATION OF OPTICAL AREA RELATIVE TO D AND E WILL BE  $\pm 0.1^\circ$ . OPTICAL AREA IS DEFINED BY THE ACTIVE PIXEL ARRAY. REFER TO THE DEVICE DATASHEET FOR TOTAL ARRAY AND FIRST ACTIVE PIXEL DEFINITIONS.
7. PARALLELISM APPLIES ONLY TO THE OPTICAL AREA.
8. OPTICAL CENTER OFFSET WITH RESPECT TO THE PACKAGE CENTER IS X=-23.56 MICRONS, Y=96.96 MICRONS  $\pm 25$  MICRONS.

DIM	MILLIMETERS	
	MIN.	MAX.
A	---	0.81
A1	0.11	0.17
A2	0.125	0.175
A3	0.421	0.461
b	0.25	0.31
D	6.198	BSC
E	6.178	BSC
e	0.65	BSC
F	0.38	0.42

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<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>ODCSP63, 6.198X6.178</b>	<b>PAGE 1 OF 2</b>



ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ. BY M. FORBIS.	06 JUN 2016
A	CHANGED PACKAGE DESCRIPTION FROM WLCSP TO ODCSP AND CASE CODE FROM 567NV TO 570BY. REQ. BY J. MILLER.	01 NOV 2016
B	MODIFIED TO LATEST DEFINITIONS. REQ. BY M. FORBIS.	05 JAN 2018

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